



FF784 - Sn/Pb SOLDER BALLS  
FFG784 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.45	<i>~</i>	3.10	2
A <sub>1</sub>	0.40	0.50	0.60	
A <sub>2</sub>	0.65	<i>~</i>	0.95	
D/E	29.00 BASIC			
D <sub>1</sub> /E <sub>1</sub>	27.00 REF			
e	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa	<i>~</i>	<i>~</i>	0.20	
ccc	<i>~</i>	<i>~</i>	0.25	
ddd	<i>~</i>	<i>~</i>	0.25	
eee	<i>~</i>	<i>~</i>	0.10	
M	28			

**NOTES:**

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. CONFORMS TO JEDEC MS-034-AAM-1

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.

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